

Quad 2-Input OR Gate

MM74HC32

General Description

The MM74HC32 OR gates utilize advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits.

All gates have buffered outputs providing high noise immunity and the ability to drive 10 LS-TTL loads. The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

- Typical Propagation Delay: 10 ns
- Wide Power Supply Range: 2 V – 6 V
- Low Quiescent Current: 20 μA maximum (74HC Series)
- Low Input Current: 1 μA Maximum
- Fanout of 10 LS-TTL Loads
- These Devices are Pb-Free, Halide Free and are RoHS Compliant

Connection Diagram

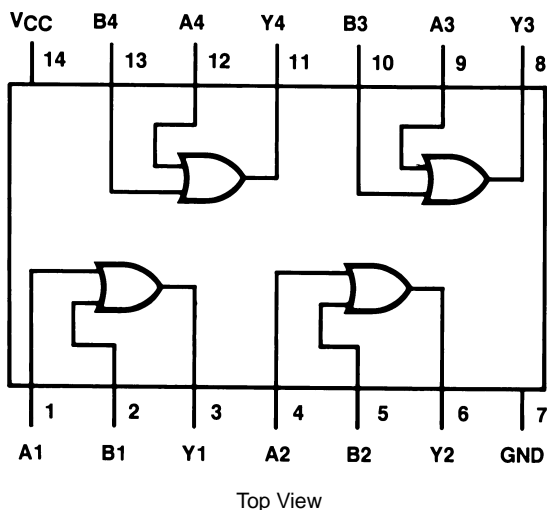


Figure 1. Pin Assignments for SOIC and TSSOP

Logic Diagram

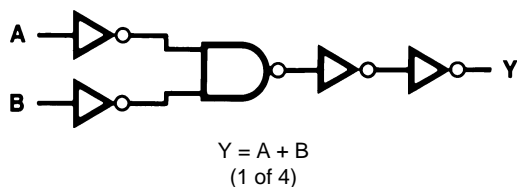
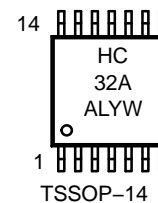
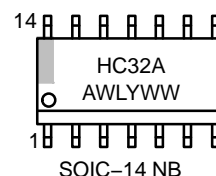


Figure 2. Logic Diagram



MARKING DIAGRAM



HC32A = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

MM74HC32

ABSOLUTE MAXIMUM RATINGS (Note 1)

| Symbol | Parameter | | Rating |
|------------------|---|-------------------|--------------------------|
| V_{CC} | Supply Voltage | | -0.5 to +7.0 V |
| V_{IN} | DC Input Voltage | | -0.5 to $V_{CC} + 0.5$ V |
| V_{OUT} | DC Output Voltage | | -0.5 to $V_{CC} + 0.5$ V |
| I_{IK}, I_{OK} | Clamp Diode Current | | ±20 mA |
| I_{OUT} | DC Output Current, per Pin | | ±25 mA |
| I_{CC} | DC V_{CC} or GND Current, per Pin | | ±50 mA |
| T_{STG} | Storage Temperature Range | | -65°C to +150°C |
| P_D | Power Dissipation | Note 2 | 600 mW |
| | | S.O. Package Only | 500 mW |
| T_L | Lead Temperature (Soldering 10 Seconds) | | 260°C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Unless otherwise specified all voltages are referenced to ground.
2. Power Dissipation temperature derating – plastic “N” package: -12 mW/°C from 65°C to 85°C.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | | Min | Max | Unit |
|-------------------|-----------------------------|------------------|-----|----------|------|
| V_{CC} | Supply Voltage | | 2 | 6 | V |
| V_{IN}, V_{OUT} | DC Input or Output Voltage | | 0 | V_{CC} | V |
| T_A | Operating Temperature Range | | -40 | +85 | °C |
| t_r, t_f | Input Rise or Fall Times | $V_{CC} = 2.0$ V | - | 1000 | ns |
| | | $V_{CC} = 4.5$ V | - | 500 | ns |
| | | $V_{CC} = 6.0$ V | - | 400 | ns |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

MM74HC32

DC CHARACTERISTICS (Note 3)

| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = 25°C | | T _A = -40°C to 85°C | | Unit |
|-----------------|-----------------------------------|---------------------|--|--|-------------------|--------------------------------|------|------|
| | | | | Typ | Guaranteed Limits | | | |
| V _{IH} | Minimum HIGH Level Input Voltage | 2.0 | | - | 1.5 | 1.5 | V | |
| | | 4.5 | | - | 3.15 | 3.15 | | |
| | | 6.0 | | - | 4.2 | 4.2 | | |
| V _{IL} | Maximum LOW Level Input Voltage | 2.0 | | - | 0.5 | 0.5 | V | |
| | | 4.5 | | - | 1.35 | 1.35 | | |
| | | 6.0 | | - | 1.8 | 1.8 | | |
| V _{OH} | Minimum HIGH Level Output Voltage | 2.0 | V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 20 μA | 2.0 | 1.9 | 1.9 | V | |
| | | 4.5 | | 4.5 | 4.4 | 4.4 | | |
| | | 6.0 | | 6.0 | 5.9 | 5.9 | | |
| | | 4.5 | V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 4.0 mA | 4.2 | 3.98 | 3.84 | | |
| | | 6.0 | | V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 5.2 mA | 5.2 | 5.48 | | 5.34 |
| V _{OL} | Maximum LOW Level Output Voltage | 2.0 | V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 20 μA | | 0 | 0.1 | 0.1 | V |
| | | 4.5 | | 0 | 0.1 | 0.1 | | |
| | | 6.0 | | 0 | 0.1 | 0.1 | | |
| | | 4.5 | V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 4.0 mA | 0.2 | 0.26 | 0.33 | | |
| | | 6.0 | | V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 5.2 mA | 0.2 | 0.26 | 0.33 | |
| I _{IN} | Maximum Input Current | 6.0 | V _{IN} = V _{CC} or GND | | - | ±0.1 | ±1.0 | μA |
| I _{CC} | Maximum Quiescent Supply Current | 6.0 | V _{IN} = V _{CC} or GND, I _{OUT} = 0 μA | - | 2.0 | 20 | μA | |

3. For a power supply of 5 V ±10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5 V. Thus the 4.5 V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5 V and 4.5 V respectively. (The V_{IH} value at 5.5 V is 3.85 V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0 V values should be used.

AC CHARACTERISTICS (V_{CC} = 5 V, T_A = 25°C, C_L = 15 pF, t_r = t_f = 6 ns)

| Symbol | Parameter | Conditions | Typ | Guaranteed Limit | Unit |
|-------------------------------------|---------------------------|------------|-----|------------------|------|
| t _{PHL} , t _{PLH} | Maximum Propagation Delay | | 10 | 18 | ns |

AC CHARACTERISTICS (V_{CC} = 2.0 V to 6.0 V, C_L = 50 pF, t_r = t_f = 6 ns (unless otherwise specified))

| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = 25°C | | T _A = -40°C to 85°C | | Unit |
|-------------------------------------|--|---------------------|------------|-----------------------|-------------------|--------------------------------|----|------|
| | | | | Typ | Guaranteed Limits | | | |
| t _{PHL} , t _{PLH} | Maximum Propagation Delay | 2.0 | | 30 | 100 | 125 | ns | |
| | | 4.5 | | 12 | 20 | 25 | | |
| | | 6.0 | | 9 | 17 | 21 | | |
| t _{TLH} , t _{THL} | Maximum Output Rise and Fall Time | 2.0 | | 30 | 75 | 95 | ns | |
| | | 4.5 | | 8 | 15 | 19 | | |
| | | 6.0 | | 7 | 13 | 16 | | |
| C _{PD} | Power Dissipation Capacitance (Note 4) | | (per gate) | 50 | - | - | pF | |
| C _{IN} | Maximum Input Capacitance | | | 5 | 10 | 10 | pF | |

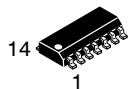
4. C_{PD} determines the no load dynamic power consumption, P_D = C_{PD} V_{CC}² f + I_{CC} V_{CC}, and the no load dynamic current consumption, I_S = C_{PD} V_{CC} f + I_{CC}.

MM74HC32

ORDERING INFORMATION

| Part Number | Package | Shipping† |
|--------------|--|--------------------------|
| MM74HC32M | SOIC-14, Case 751A-03 (Pb-Free, Halide-Free) | 55 Units / Tube |
| MM74HC32MTC | TSSOP-14, Case 948G-01 (Pb-Free, Halide Free) | 96 Units / Tube |
| MM74HC32MX | SOIC-14, Case 751EF (Pb-Free, Halide-Free) | 2500 Units / Tape & Reel |
| MM74HC32MTCX | TSSOP-14, Case 948G-01 (Pb-Free, Halide Free) | 2500 Units / Tape & Reel |

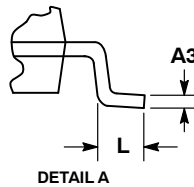
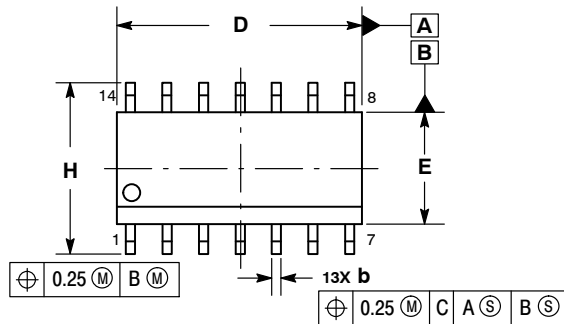
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



SCALE 1:1

SOIC-14 NB
CASE 751A-03
ISSUE L

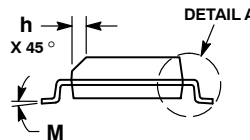
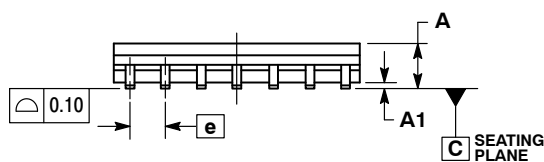
DATE 03 FEB 2016



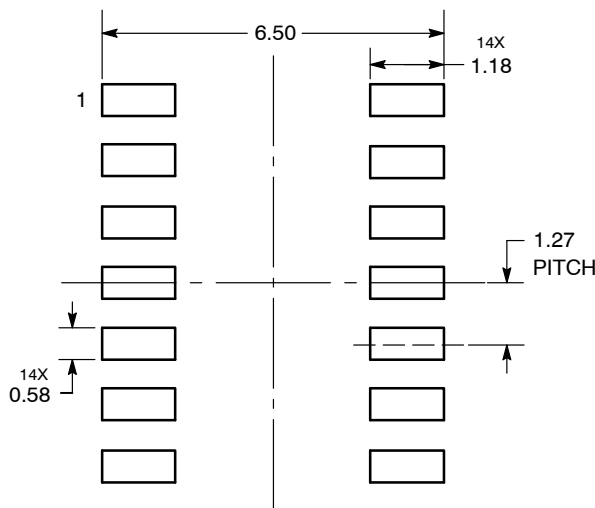
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.35 | 1.75 | 0.054 | 0.068 |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 |
| A3 | 0.19 | 0.25 | 0.008 | 0.010 |
| b | 0.35 | 0.49 | 0.014 | 0.019 |
| D | 8.55 | 8.75 | 0.337 | 0.344 |
| E | 3.80 | 4.00 | 0.150 | 0.157 |
| e | 1.27 BSC | | 0.050 BSC | |
| H | 5.80 | 6.20 | 0.228 | 0.244 |
| h | 0.25 | 0.50 | 0.010 | 0.019 |
| L | 0.40 | 1.25 | 0.016 | 0.049 |
| M | 0° | 7° | 0° | 7° |



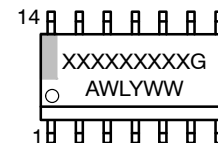
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

| | | |
|------------------|-------------|---|
| DOCUMENT NUMBER: | 98ASB42565B | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION: | SOIC-14 NB | PAGE 1 OF 2 |

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

SOIC-14
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. NO CONNECTION
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 2:
 CANCELLED

STYLE 3:
 PIN 1. NO CONNECTION
 2. ANODE
 3. ANODE
 4. NO CONNECTION
 5. ANODE
 6. NO CONNECTION
 7. ANODE
 8. ANODE
 9. ANODE
 10. NO CONNECTION
 11. ANODE
 12. ANODE
 13. NO CONNECTION
 14. COMMON CATHODE

STYLE 4:
 PIN 1. NO CONNECTION
 2. CATHODE
 3. CATHODE
 4. NO CONNECTION
 5. CATHODE
 6. NO CONNECTION
 7. CATHODE
 8. CATHODE
 9. CATHODE
 10. NO CONNECTION
 11. CATHODE
 12. CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 5:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. COMMON ANODE
 8. COMMON CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 6:
 PIN 1. CATHODE
 2. CATHODE
 3. CATHODE
 4. CATHODE
 5. CATHODE
 6. CATHODE
 7. CATHODE
 8. ANODE
 9. ANODE
 10. ANODE
 11. ANODE
 12. ANODE
 13. ANODE
 14. ANODE

STYLE 7:
 PIN 1. ANODE/CATHODE
 2. COMMON ANODE
 3. COMMON CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. COMMON CATHODE
 12. COMMON ANODE
 13. ANODE/CATHODE
 14. ANODE/CATHODE

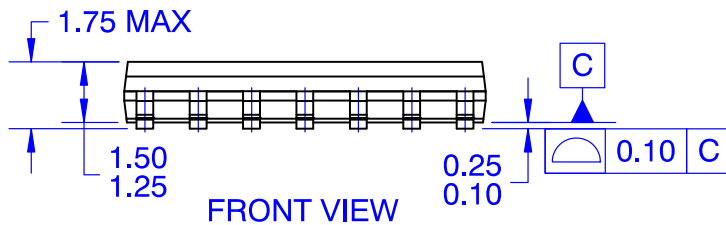
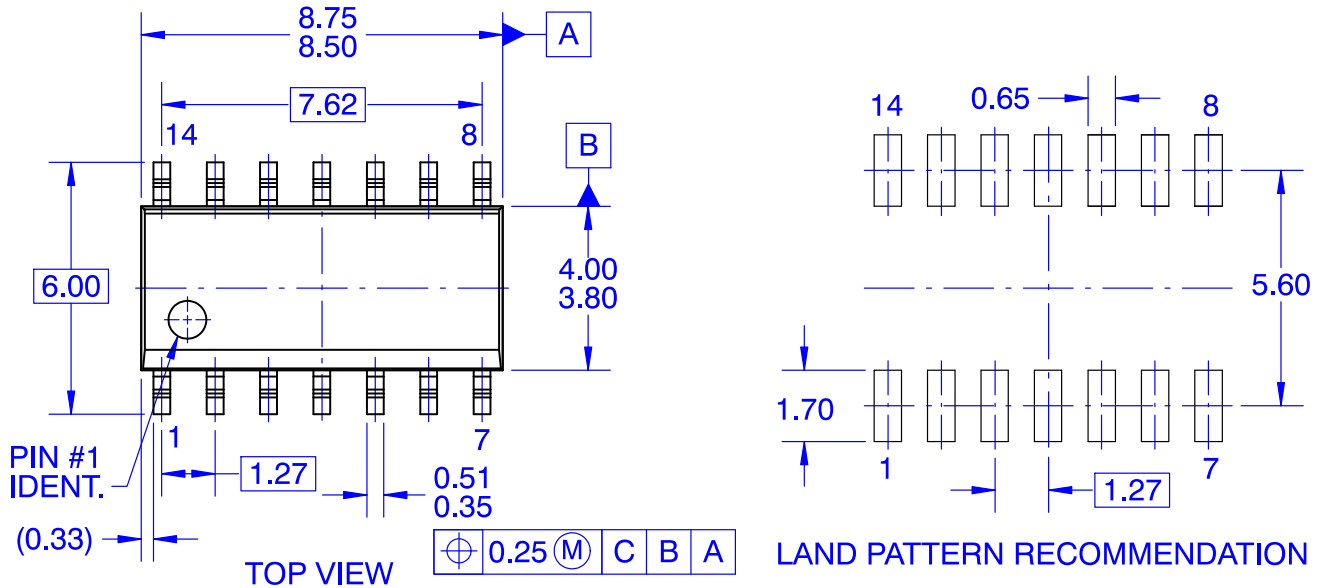
STYLE 8:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. COMMON ANODE
 8. COMMON ANODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. NO CONNECTION
 12. ANODE/CATHODE
 13. ANODE/CATHODE
 14. COMMON CATHODE

| | | |
|-------------------------|--------------------|---|
| DOCUMENT NUMBER: | 98ASB42565B | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION: | SOIC-14 NB | PAGE 2 OF 2 |

onsemi and **ONSEMI** are trademarks of Semiconductor Components Industries, LLC dba **onsemi** or its subsidiaries in the United States and/or other countries. **onsemi** reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

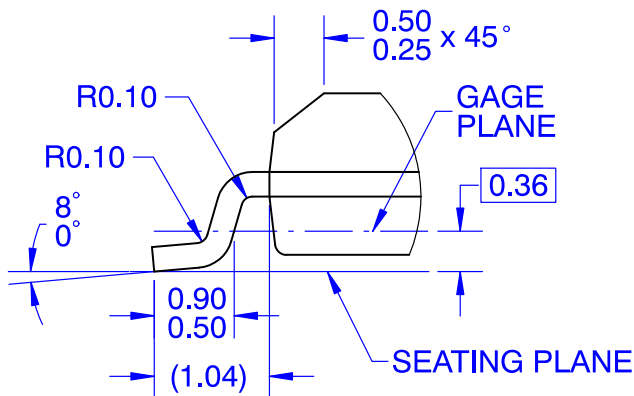
SOIC14
CASE 751EF
ISSUE O

DATE 30 SEP 2016



NOTES:

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- D. LAND PATTERN STANDARD: SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009



DETAIL A
SCALE 16 : 1

| | | |
|-------------------------|--------------------|--|
| DOCUMENT NUMBER: | 98AON13739G | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION: | SOIC14 | PAGE 1 OF 1 |

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales